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U.S. DEPARTMENT OF COMMERCE

2390 U.S. PTO  
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2001 Staas & Halsey LLP

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):  
Hideaki SAKAGUCHI  
Mitsutoshi HIGASHI
2. Name and Address of receiving party(ies):  
  
SHINKO ELECTRIC INDUSTRIES CO., LTD.  
80 Oshimada-machi  
Nagano-shi 381-2287 Japan
3. Nature of conveyance:  
☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Other: \_\_\_\_\_  
Execution Date(s): January 5, 2004
4. Application number(s) or patent number(s):  
☒ This document is being filed together with a new application:  
(a) The execution date(s) of the application is/are: January 5, 2004  
(b) The title is: METHOD FOR DICING WAFER  
OR  
☐ This document is being filed after filing of the application:  
(a) Patent Application No(s). /, filed \_\_\_\_\_; or  
(b) Patent No(s). \_\_\_\_\_, issued \_\_\_\_\_
5. Name and address of party to whom correspondence concerning document should be mailed:  
STAAS & HALSEY LLP Our Docket: 300.1144  
Attention: H. J. Staas  
1201 New York Ave., N.W., Suite 700  
Washington, D.C. 20005
6. Total number of applications and patents involved: 1
7. Total fee (37 CFR 3.41)..... (\$ 40.00 per Assignment)  
☒ Enclosed  
☐ Authorized to be charged to deposit account.
8. Deposit Account No.: 19-3935 (Any underpayment is authorized to be charged to this Deposit Account)  
(Attach duplicate copy of this page if paying by deposit account)
9. Statement and signature.  
*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*

H. J. Staas, Reg. No. 22,010

Name of Person Signing

Signature

January 15, 2004

Date

Total number of pages including cover sheet: 2

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# U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter "ASSIGNOR") by

(Insert  
ASSIGNEE's  
Name(s)  
Address(es))

SHINKO ELECTRIC INDUSTRIES CO., LTD.

80, Oshimada-machi, Nagano-shi, Nagano 381-2287, Japan

(hereinafter "ASSIGNEE"), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled

(Title of  
Invention)

METHOD FOR DICING WAFER

relating to International Patent Application PCT/JP \_\_\_\_\_/\_\_\_\_\_ and/or for which application for Letters Patent of the United States was executed on even date herewith or, if not so executed, was:

(Insert date  
of execution  
of application,  
if not  
concurrent)

(a) executed on \_\_\_\_\_;

(b) filed on \_\_\_\_\_,  
Serial No. \_\_\_\_\_/\_\_\_\_\_;

( \_\_\_\_\_ ) is hereby authorized to insert in (b) the specified data, when known.

and to said application and all Letters Patent(s) of the United States granted on said application and any continuation, division, renewal, substitute, reissue or reexamination application based thereon, for the full term or terms for which the said Letters Patent(s) may be granted and including any extensions thereof (collectively, hereinafter, "said application(s) and Letters Patent(s)").

The ASSIGNOR agree(s), when requested by said ASSIGNEE and without charge to but at the expense of said ASSIGNEE, to do all acts which the ASSIGNEE may deem necessary, desirable or expedient, for securing, maintaining and enforcing protection for said invention, including in the preparation and prosecution of said application(s) and the issuance of said Letters Patent(s), in any interference, reissue, reexamination, or public use proceeding, and in any litigation or other legal proceeding which may arise or be declared in relation to same, such acts to include but not be limited to executing all papers, including separate assignments and declarations, taking all rightful oaths, providing sworn testimony, and obtaining and producing evidence.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

(Signatures)

1) Hideaki Sakaguchi  
(SIGNATURE)

Hideaki Sakaguchi  
(TYPE NAME)

January 5, 2004  
(DATE)

2) Mitsutoshi Higashi  
(SIGNATURE)

Mitsutoshi Higashi  
(TYPE NAME)

January 5, 2004  
(DATE)

3) \_\_\_\_\_  
(SIGNATURE)

(TYPE NAME)

(DATE)

4) \_\_\_\_\_  
(SIGNATURE)

(TYPE NAME)

(DATE)

5) \_\_\_\_\_  
(SIGNATURE)

(TYPE NAME)

(DATE)

6) \_\_\_\_\_  
(SIGNATURE)

(TYPE NAME)

(DATE)

7) \_\_\_\_\_  
(SIGNATURE)

(TYPE NAME)

(DATE)

8) \_\_\_\_\_  
(SIGNATURE)

(TYPE NAME)

(DATE)